

## Patent Abstracts of Japan

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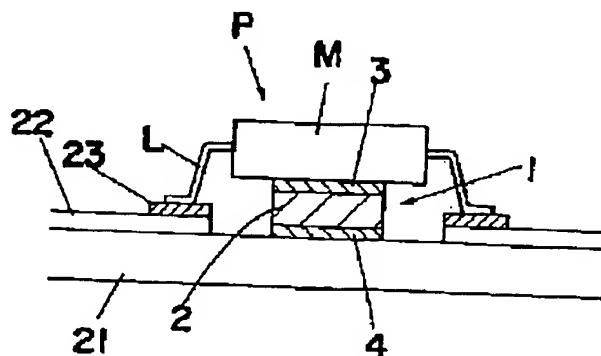
APPLICATION DATE : 16-06-92

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APPLICANT : MATSUSHITA ELECTRIC IND CO LTD;

INVENTOR : KADOUE EIGO;

INT.CL. : H05K 3/34 C09J 7/02

TITLE : PIECE FOR TEMPORARILY FIXING  
ELECTRONIC PART

ABSTRACT : PURPOSE: To acquire a piece for temporarily fixing an electronic part which can temporarily fix an electronic part to a substrate firmly until soldering of the electronic part is finished and which can be removed from the substrate readily when soldering is defective or a kind of the electronic part is changed because of design modification.

CONSTITUTION: Adhesion layers 3, 4 are formed in both sides of a piece 1; the upper adhesion layer 3 is a heat resistant adhesion material and the lower adhesion layer 4 is a thermally soluble adhesion material. Therefore, an electronic part P can be firmly adhered to a substrate 21 and can be readily removed from the substrate 12 when soldering is defective.

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